

## N - CHANNEL ENHANCEMENT MODE FAST POWER MOS TRANSISTOR

PRELIMINARY DATA

| TYPE      | V <sub>DSS</sub> | R <sub>DS(on)</sub> | I <sub>D</sub> |
|-----------|------------------|---------------------|----------------|
| STU10NA50 | 500 V            | < 0.6 Ω             | 10.2 A         |

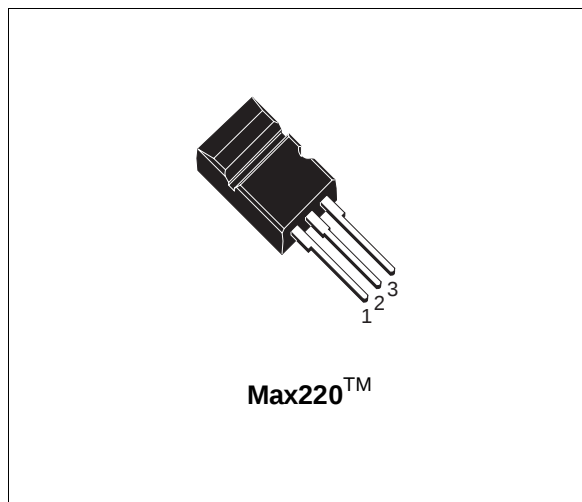
- TYPICAL R<sub>DS(on)</sub> = 0.5 Ω
- ± 30V GATE TO SOURCE VOLTAGE RATING
- REPETITIVE AVALANCHE TESTED
- LOW INTRINSIC CAPACITANCE
- 100% AVALANCHE TESTED
- GATE CHARGE MINIMIZED
- REDUCED THRESHOLD VOLTAGE SPREAD

### DESCRIPTION

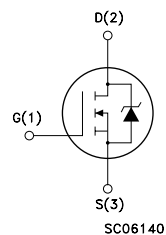
The Max220™ package is a new high volume power package exhibiting the same footprint as the industry standard TO-220, but designed to accomodate much larger silicon chips, normally supplied in bigger packages. The increased die capacity makes the device ideal to reduce component count in multiple paralleled TO-220 designs and save board space with respect to larger packages.

### APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES (UPS)



### INTERNAL SCHEMATIC DIAGRAM



### ABSOLUTE MAXIMUM RATINGS

| Symbol              | Parameter                                             | Value      | Unit |
|---------------------|-------------------------------------------------------|------------|------|
| V <sub>DS</sub>     | Drain-source Voltage (V <sub>GS</sub> = 0)            | 500        | V    |
| V <sub>DGR</sub>    | Drain- gate Voltage (R <sub>GS</sub> = 20 kΩ)         | 500        | V    |
| V <sub>GS</sub>     | Gate-source Voltage                                   | ± 30       | V    |
| I <sub>D</sub>      | Drain Current (continuous) at T <sub>c</sub> = 25 °C  | 10.2       | A    |
| I <sub>D</sub>      | Drain Current (continuous) at T <sub>c</sub> = 100 °C | 6.4        | A    |
| I <sub>DM</sub> (•) | Drain Current (pulsed)                                | 40.8       | A    |
| P <sub>tot</sub>    | Total Dissipation at T <sub>c</sub> = 25 °C           | 145        | W    |
|                     | Derating Factor                                       | 1.16       | W/°C |
| T <sub>stg</sub>    | Storage Temperature                                   | -65 to 150 | °C   |
| T <sub>j</sub>      | Max. Operating Junction Temperature                   | 150        | °C   |

(•) Pulse width limited by safe operating area

**THERMAL DATA**

|                       |                                                |     |      |      |
|-----------------------|------------------------------------------------|-----|------|------|
| R <sub>thj-case</sub> | Thermal Resistance Junction-case               | Max | 0.86 | °C/W |
| R <sub>thj-amb</sub>  | Thermal Resistance Junction-ambient            | Max | 30   | °C/W |
| R <sub>thc-sink</sub> | Thermal Resistance Case-sink                   | Typ | 0.1  | °C/W |
| T <sub>l</sub>        | Maximum Lead Temperature For Soldering Purpose |     | 300  | °C   |

**AVALANCHE CHARACTERISTICS**

| Symbol          | Parameter                                                                                                                    | Max Value | Unit |
|-----------------|------------------------------------------------------------------------------------------------------------------------------|-----------|------|
| I <sub>AR</sub> | Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T <sub>j</sub> max, δ < 1%)                          | 10.2      | A    |
| E <sub>AS</sub> | Single Pulse Avalanche Energy (starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)   | 520       | mJ   |
| E <sub>AR</sub> | Repetitive Avalanche Energy (pulse width limited by T <sub>j</sub> max, δ < 1%)                                              | 24        | mJ   |
| I <sub>AR</sub> | Avalanche Current, Repetitive or Not-Repetitive (T <sub>c</sub> = 100 °C, pulse width limited by T <sub>j</sub> max, δ < 1%) | 6.8       | A    |

**ELECTRICAL CHARACTERISTICS** (T<sub>case</sub> = 25 °C unless otherwise specified)

**OFF**

| Symbol               | Parameter                                             | Test Conditions                                                                            | Min. | Typ. | Max.        | Unit     |
|----------------------|-------------------------------------------------------|--------------------------------------------------------------------------------------------|------|------|-------------|----------|
| V <sub>(BR)DSS</sub> | Drain-source Breakdown Voltage                        | I <sub>D</sub> = 250 μA V <sub>GS</sub> = 0                                                | 500  |      |             | V        |
| I <sub>DSS</sub>     | Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0) | V <sub>DS</sub> = Max Rating<br>V <sub>DS</sub> = Max Rating x 0.8 T <sub>c</sub> = 100 °C |      |      | 250<br>1000 | μA<br>μA |
| I <sub>GSS</sub>     | Gate-body Leakage Current (V <sub>DS</sub> = 0)       | V <sub>GS</sub> = ± 30 V                                                                   |      |      | ± 100       | nA       |

**ON (\*)**

| Symbol              | Parameter                         | Test Conditions                                                                                                   | Min. | Typ. | Max.       | Unit   |
|---------------------|-----------------------------------|-------------------------------------------------------------------------------------------------------------------|------|------|------------|--------|
| V <sub>GS(th)</sub> | Gate Threshold Voltage            | V <sub>DS</sub> = V <sub>GS</sub> I <sub>D</sub> = 250 μA                                                         | 2.25 | 3    | 3.75       | V      |
| R <sub>DS(on)</sub> | Static Drain-source On Resistance | V <sub>GS</sub> = 10 V I <sub>D</sub> = 5 A<br>V <sub>GS</sub> = 10 V I <sub>D</sub> = 5 A T <sub>c</sub> = 100°C |      | 0.5  | 0.6<br>1.2 | Ω<br>Ω |
| I <sub>D(on)</sub>  | On State Drain Current            | V <sub>DS</sub> > I <sub>D(on)</sub> x R <sub>DS(on)max</sub><br>V <sub>GS</sub> = 10 V                           | 10.2 |      |            | A      |

**DYNAMIC**

| Symbol              | Parameter                    | Test Conditions                                                                    | Min. | Typ. | Max. | Unit |
|---------------------|------------------------------|------------------------------------------------------------------------------------|------|------|------|------|
| g <sub>fs</sub> (*) | Forward Transconductance     | V <sub>DS</sub> > I <sub>D(on)</sub> x R <sub>DS(on)max</sub> I <sub>D</sub> = 5 A | 6    | 9    |      | S    |
| C <sub>iss</sub>    | Input Capacitance            | V <sub>DS</sub> = 25 V f = 1 MHz V <sub>GS</sub> = 0                               |      | 1750 | 2500 | pF   |
| C <sub>oss</sub>    | Output Capacitance           |                                                                                    |      | 250  | 370  | pF   |
| C <sub>rss</sub>    | Reverse Transfer Capacitance |                                                                                    |      | 80   | 130  | pF   |

**ELECTRICAL CHARACTERISTICS** (continued)**SWITCHING ON**

| Symbol         | Parameter             | Test Conditions                                                                          | Min. | Typ. | Max. | Unit       |
|----------------|-----------------------|------------------------------------------------------------------------------------------|------|------|------|------------|
| $t_{d(on)}$    | Turn-on Time          | $V_{DD} = 250\text{ V}$ $I_D = 5\text{ A}$                                               |      | 20   | 28   | ns         |
| $t_r$          | Rise Time             | $R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$                                               |      | 32   | 45   | ns         |
| $(di/dt)_{on}$ | Turn-on Current Slope | $V_{DD} = 400\text{ V}$ $I_D = 10\text{ A}$<br>$R_G = 47\ \Omega$ $V_{GS} = 10\text{ V}$ |      | 190  |      | A/ $\mu$ s |
| $Q_g$          | Total Gate Charge     | $V_{DD} = 400\text{ V}$ $I_D = 10\text{ A}$ $V_{GS} = 10\text{ V}$                       |      | 80   | 110  | nC         |
| $Q_{gs}$       | Gate-Source Charge    |                                                                                          |      | 12   |      | nC         |
| $Q_{gd}$       | Gate-Drain Charge     |                                                                                          |      | 37   |      | nC         |

**SWITCHING OFF**

| Symbol        | Parameter             | Test Conditions                             | Min. | Typ. | Max. | Unit |
|---------------|-----------------------|---------------------------------------------|------|------|------|------|
| $t_{r(Voff)}$ | Off-voltage Rise Time | $V_{DD} = 400\text{ V}$ $I_D = 10\text{ A}$ |      | 16   | 22   | ns   |
| $t_f$         | Fall Time             | $R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$  |      | 12   | 18   | ns   |
| $t_c$         | Cross-over Time       |                                             |      | 30   | 42   | ns   |

**SOURCE DRAIN DIODE**

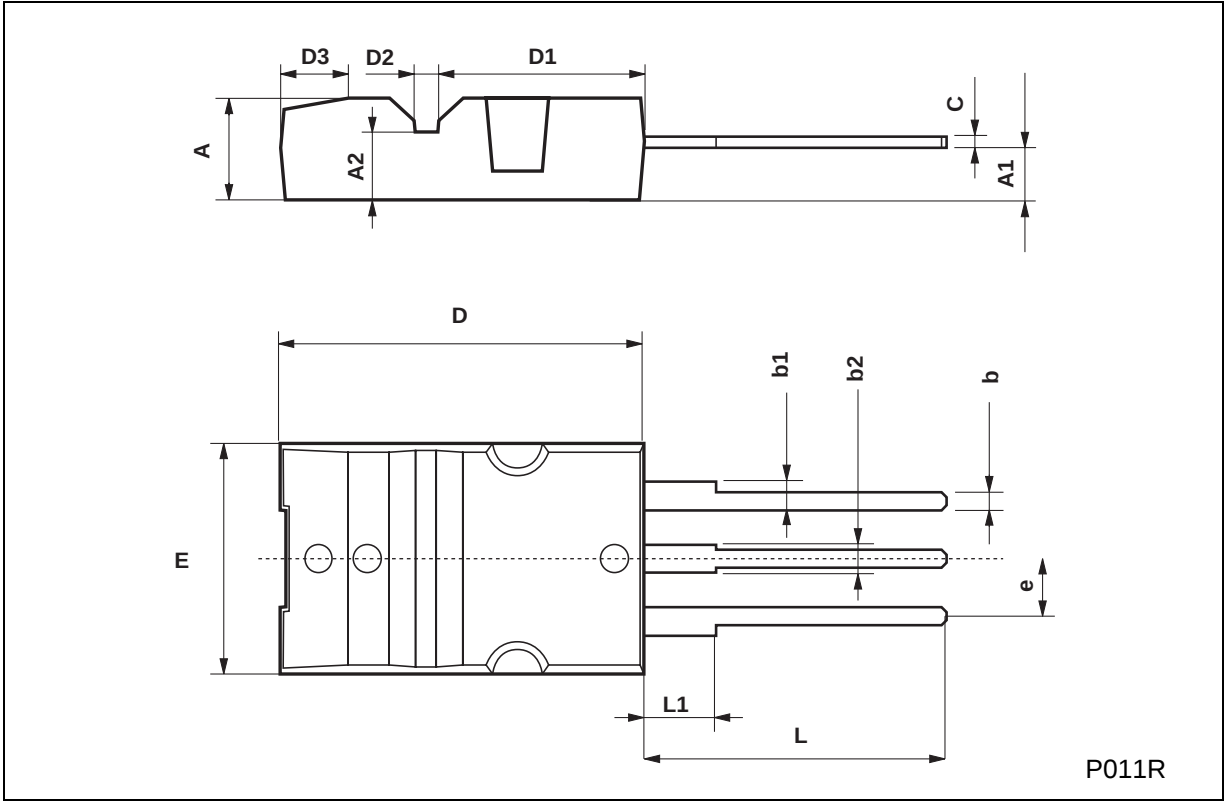
| Symbol             | Parameter                     | Test Conditions                                                                                                        | Min. | Typ. | Max. | Unit          |
|--------------------|-------------------------------|------------------------------------------------------------------------------------------------------------------------|------|------|------|---------------|
| $I_{SD}$           | Source-drain Current          |                                                                                                                        |      |      | 10.2 | A             |
| $I_{SDM}(\bullet)$ | Source-drain Current (pulsed) |                                                                                                                        |      |      | 40.8 | A             |
| $V_{SD} (*)$       | Forward On Voltage            | $I_{SD} = 10\text{ A}$ $V_{GS} = 0$                                                                                    |      |      | 1.6  | V             |
| $t_{rr}$           | Reverse Recovery Time         | $I_{SD} = 10\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$<br>$V_{DD} = 100\text{ V}$ $T_J = 150\text{ }^\circ\text{C}$ |      | 600  |      | ns            |
| $Q_{rr}$           | Reverse Recovery Charge       |                                                                                                                        |      | 10.2 |      | $\mu\text{C}$ |
| $I_{RRM}$          | Reverse Recovery Current      |                                                                                                                        |      | 34   |      | A             |

(\*) Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5 %

(\bullet) Pulse width limited by safe operating area

Max220 MECHANICAL DATA

| DIM. | mm    |      |       | inch  |       |       |
|------|-------|------|-------|-------|-------|-------|
|      | MIN.  | TYP. | MAX.  | MIN.  | TYP.  | MAX.  |
| A    | 4.3   |      | 4.6   | 0.169 |       | 0.181 |
| A1   | 2.2   |      | 2.4   | 0.087 |       | 0.094 |
| A2   | 2.9   |      | 3.1   | 0.114 |       | 0.122 |
| b    | 0.7   |      | 0.93  | 0.027 |       | 0.036 |
| b1   | 1.25  |      | 1.4   | 0.049 |       | 0.055 |
| b2   | 1.2   |      | 1.38  | 0.047 |       | 0.054 |
| c    | 0.45  |      | 0.6   |       | 0.18  | 0.023 |
| D    | 15.9  |      | 16.3  |       | 0.626 | 0.641 |
| D1   | 9     |      | 9.35  | 0.354 |       | 0.368 |
| D2   | 0.8   |      | 1.2   | 0.031 |       | 0.047 |
| D3   | 2.8   |      | 3.2   | 0.110 |       | 0.126 |
| e    | 2.44  |      | 2.64  | 0.096 |       | 0.104 |
| E    | 10.05 |      | 10.35 | 0.396 |       | 0.407 |
| L    | 13.2  |      | 13.6  | 0.520 |       | 0.535 |
| L1   | 3     |      | 3.4   | 0.118 |       | 0.133 |



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